

# TSD60R380S1

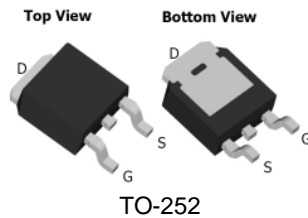
## 600V 10.6A N-Channel SJ-MOSFET

### General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme  $dv/dt$  rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

### Features

- 650V @ $T_J = 150^\circ\text{C}$
- Typ.  $R_{DS(on)} = 0.34\Omega$
- Ultra Low gate charge (typ.  $Q_g = 38\text{nC}$ )
- 100% avalanche tested



### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current	-Continuous ( $TC = 25^\circ\text{C}$ )	10.6
		-Continuous ( $TC = 100^\circ\text{C}$ )	6.7
$I_{DM}$	Drain Current – Pulsed (Note 1)	32	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	210	mJ
$I_{AR}$	Avalanche Current (Note 1)	1.8	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	0.32	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	15	V/ns
$P_D$	Power Dissipation ( $TC = 25^\circ\text{C}$ )		83
		-Derate above $25^\circ\text{C}$	1.5
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.5	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	$^\circ\text{C/W}$

# Electrical Characteristics TC = 25 °C unless otherwise noted

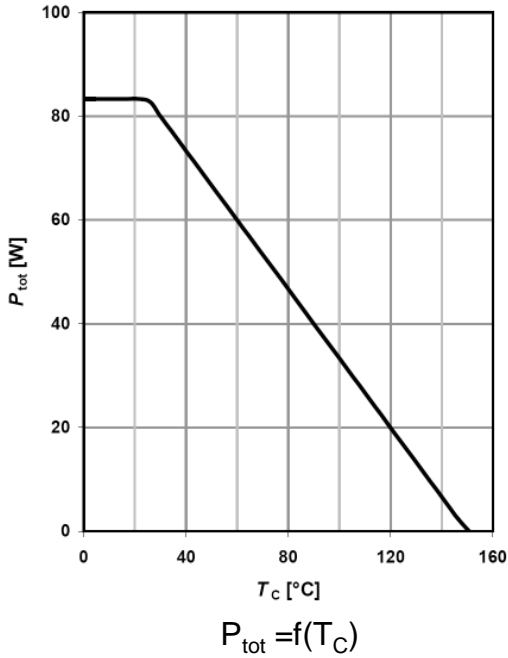
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 25 °C	600	--	--	V
		V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 150 °C	--	650	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25 °C	--	0.6	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V -T <sub>J</sub> = 150 °C	--	-- 10	1 --	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.5	--	4.5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5.5A	--	0.34	0.38	Ω
g <sub>FS</sub>	Forward Trans conductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 5.5A (Note 4)	--	16	--	S
R <sub>g</sub>	Gate resistance	f=1 MHz, open drain	--	3	--	Ω
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	--	680	--	pF
C <sub>oss</sub>	Output Capacitance		--	240	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	7	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 400V, I <sub>D</sub> = 5.5A R <sub>G</sub> = 20Ω (Note 4, 5)	--	15	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	10	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	110	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	9	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 480V, I <sub>D</sub> = 5.5A V <sub>GS</sub> = 10V (Note 4, 5)	--	38	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	4	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	4.2	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	11	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	30	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>F</sub> = 5.5A	--	0.9	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>F</sub> = 5.5A di <sub>F</sub> /dt = 100A/μs (Note 4)	--	270	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	3.3	--	μC

**NOTES:**

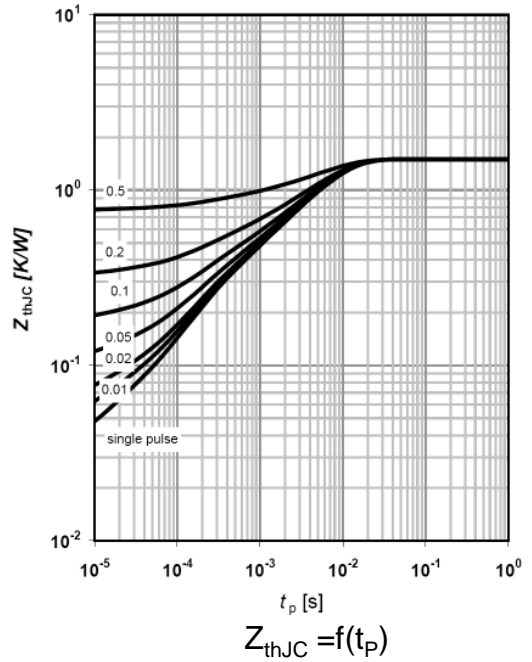
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I<sub>AS</sub>=1.8A, V<sub>DD</sub>=50V, Starting T<sub>J</sub>=25 °C
3. I<sub>SD</sub>≤10.6A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25 °C
4. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

# Typical Performance Characteristics

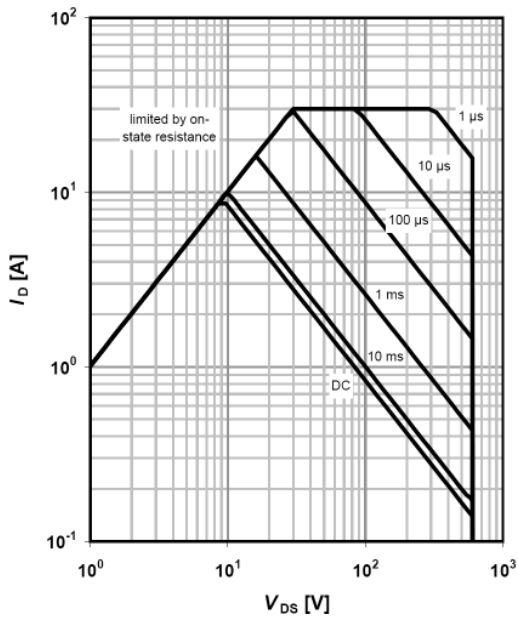
Power dissipation



Max. transient thermal impedance

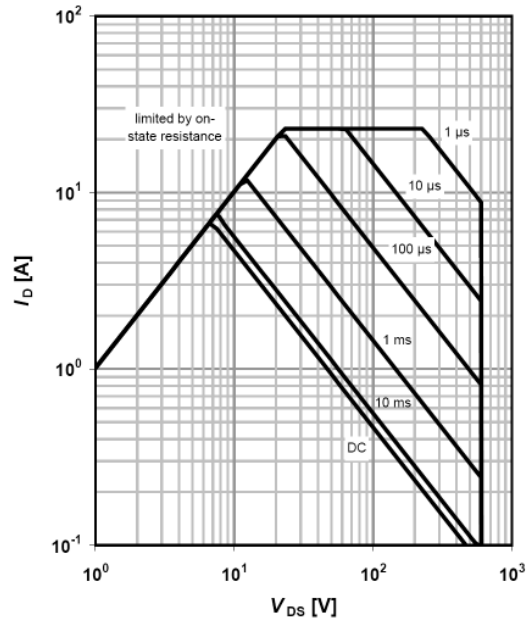


Safe operating area  $T_c = 25\text{ }^\circ\text{C}$



$I_D = f(V_{DS}); T_c = 25\text{ }^\circ\text{C}; V_{GS} > 7\text{V};$   
 $D = 0; \text{parameter } t_p$

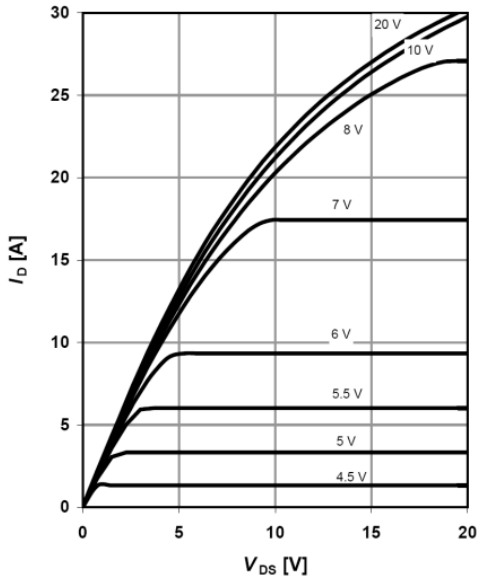
Safe operating area  $T_c = 80\text{ }^\circ\text{C}$



$I_D = f(V_{DS}); T_c = 80\text{ }^\circ\text{C}; V_{GS} > 7\text{V};$   
 $D = 0; \text{parameter } t_p$

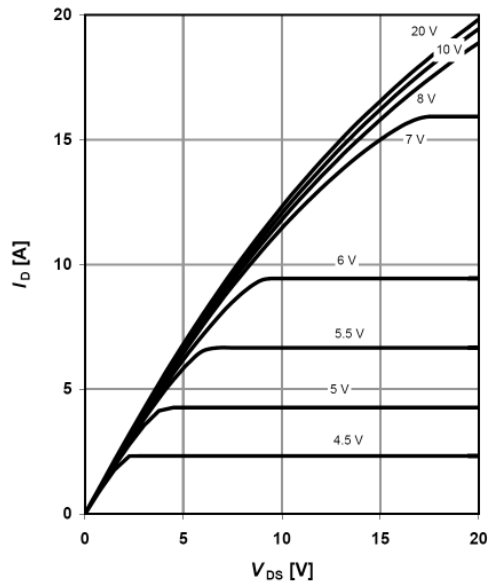
# Typical Performance Characteristics

Typ. output characteristics  $T_j=25\text{ }^\circ\text{C}$



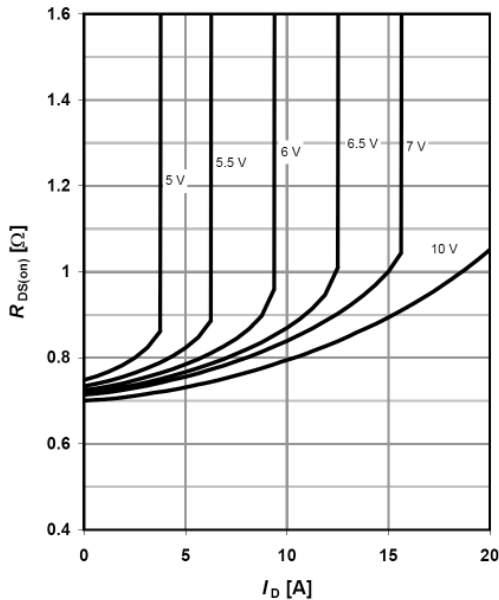
$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C}$  ; parameter:  $V_{GS}$

Typ. output characteristics  $T_j=125\text{ }^\circ\text{C}$



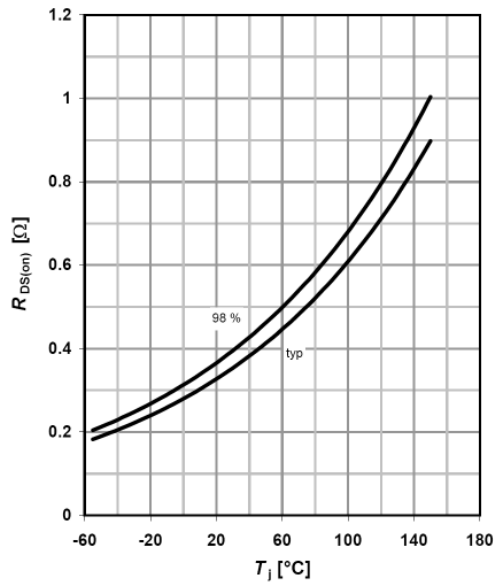
$I_D=f(V_{DS}); T_j=125\text{ }^\circ\text{C}$  ; parameter:  $V_{GS}$

Typ. drain-source on-state resistance



$R_{DS(on)}=f(I_D); T_j=125\text{ }^\circ\text{C}$  ;  
parameter:  $V_{GS}$

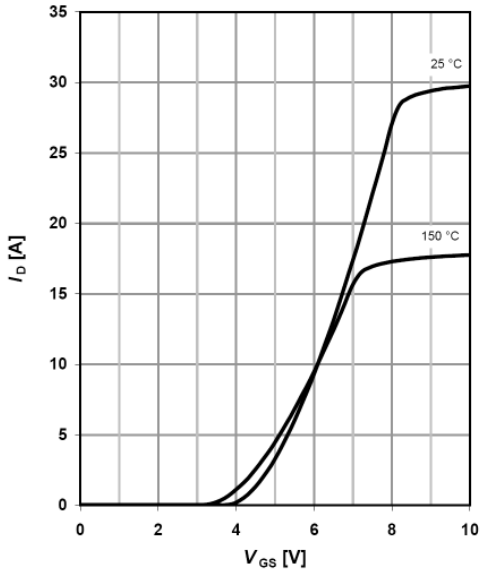
Typ. drain-source on-state resistance



$R_{DS(on)}=f(T_j); I_D=3.8\text{ A}; V_{GS}=10\text{ V}$

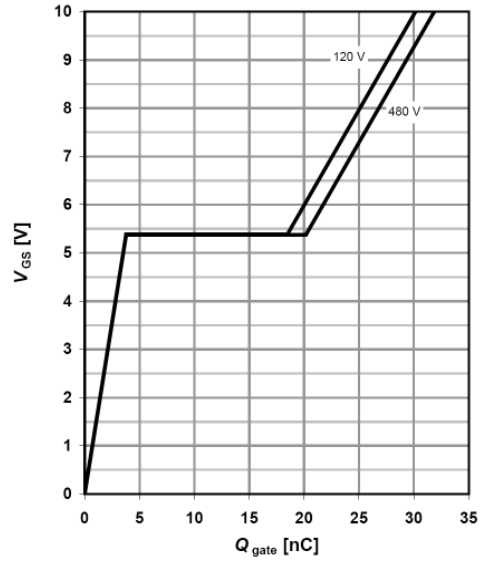
# Typical Performance Characteristics

Typ. transfer characteristics



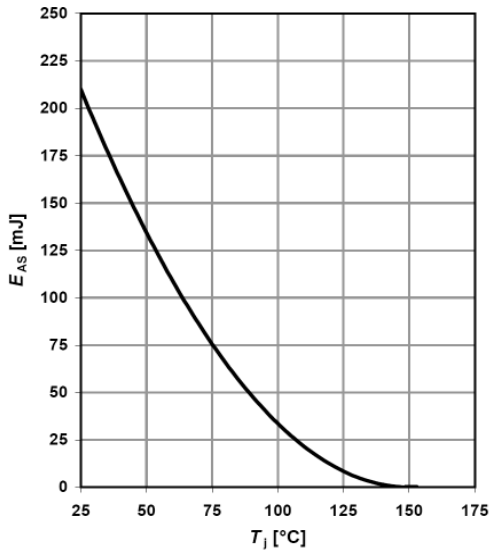
$I_D = f(V_{GS}); V_{DS} = 20V$

Typ. gate charge



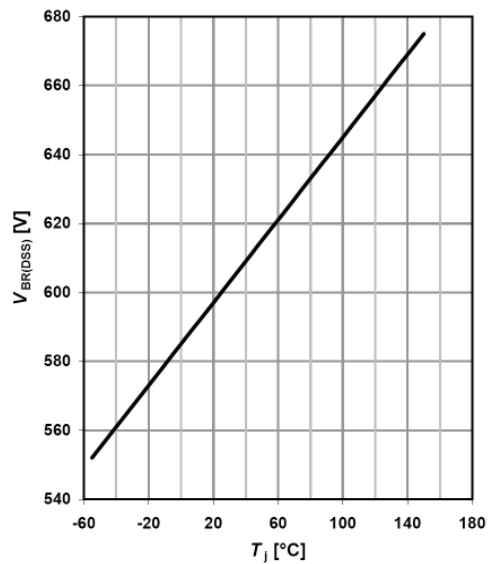
$V_{GS} = f(Q_g), I_D = 4.8 A \text{ pulsed}$

Avalanche energy



$E_{AS} = f(T_j); I_D = 1.8 A; V_{DD} = 50 V$

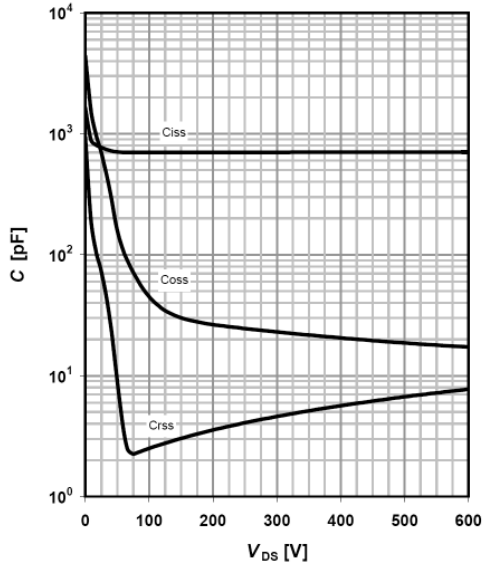
Drain-source breakdown voltage



$V_{BR(DSS)} = f(T_j); I_D = 0.25 mA$

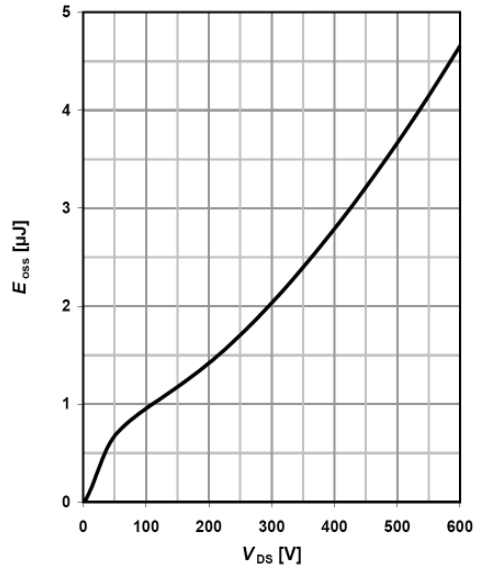
# Typical Performance Characteristics

Typ. capacitances



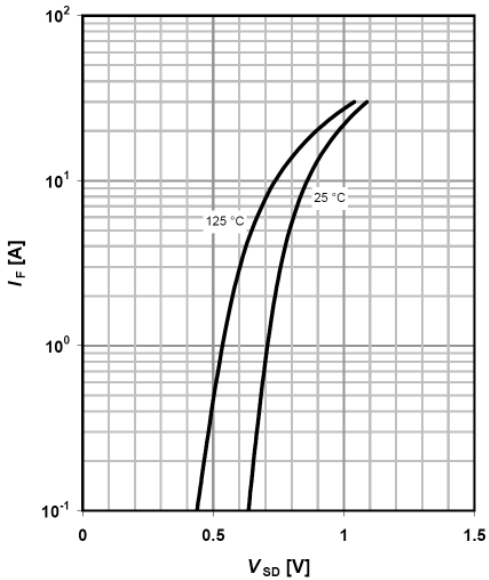
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$

Typ.  $C_{oss}$  stored energy



$E_{OSS}=f(V_{DS})$

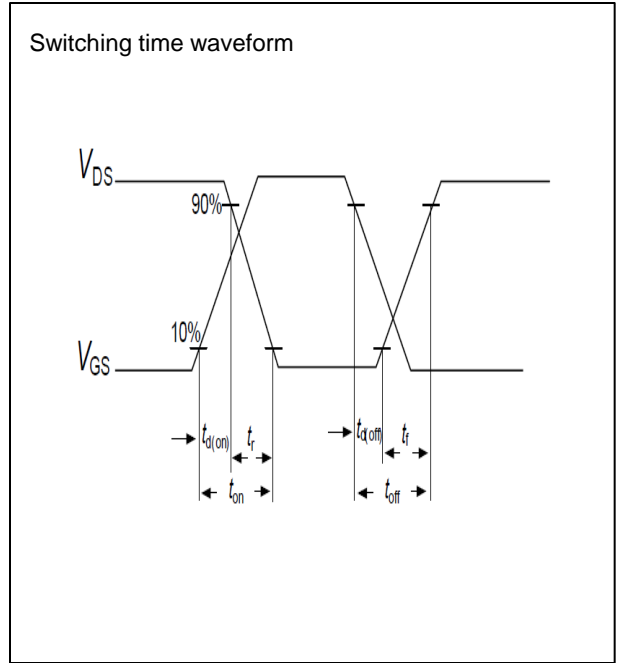
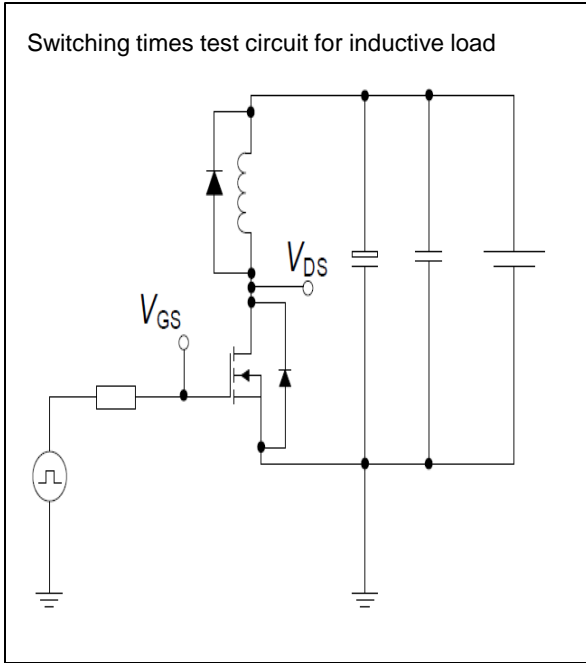
## Forward characteristics of reverse diode



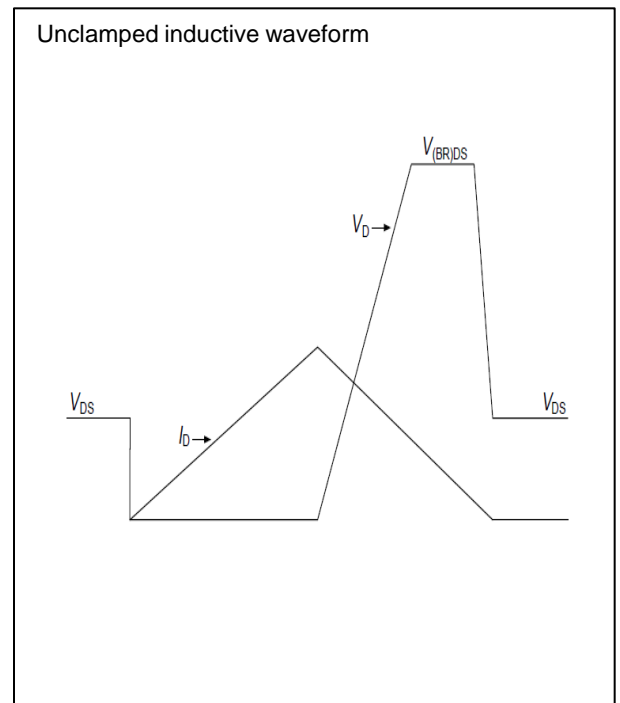
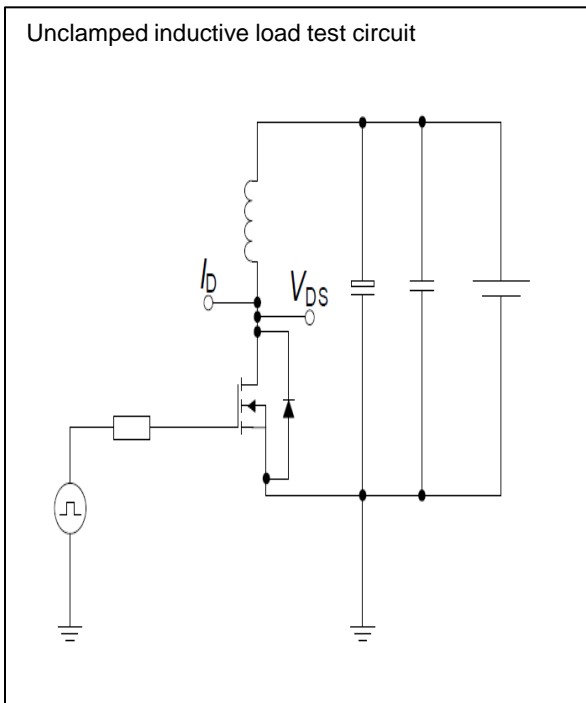
$I_F=f(V_{SD}); \text{parameter: } T_j$

# Test circuits

## Switching times test circuit and waveform for inductive load

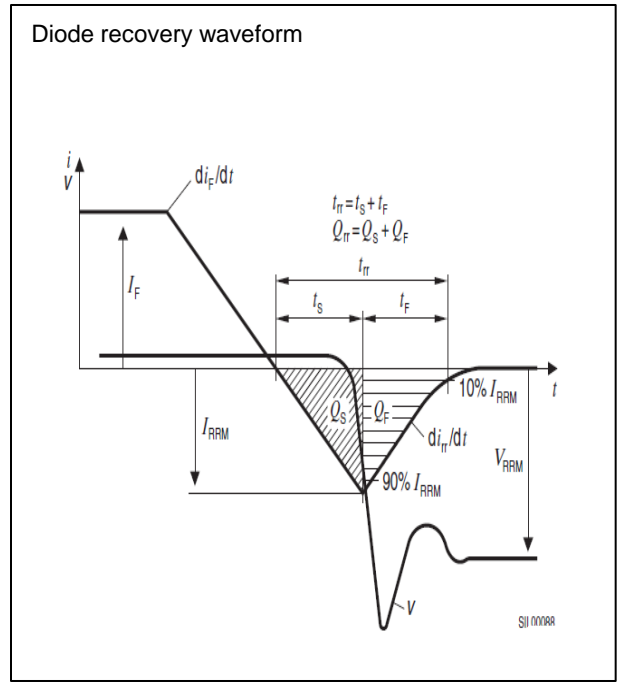
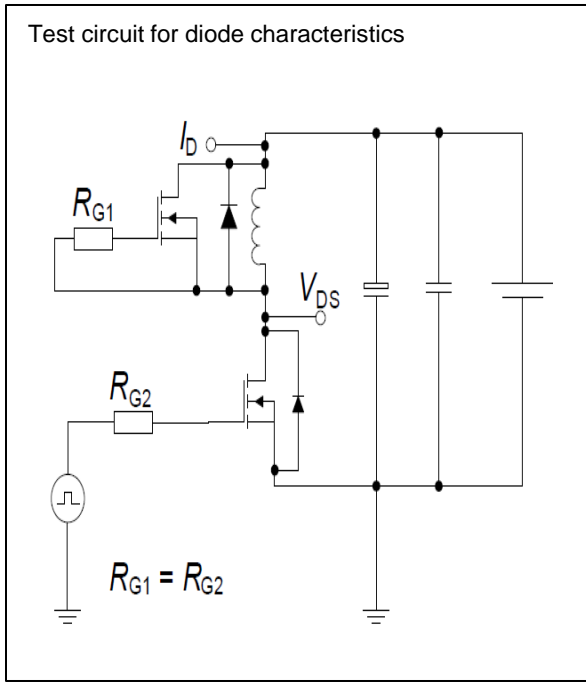


## Unclamped inductive load test circuit and waveform



# Test circuits

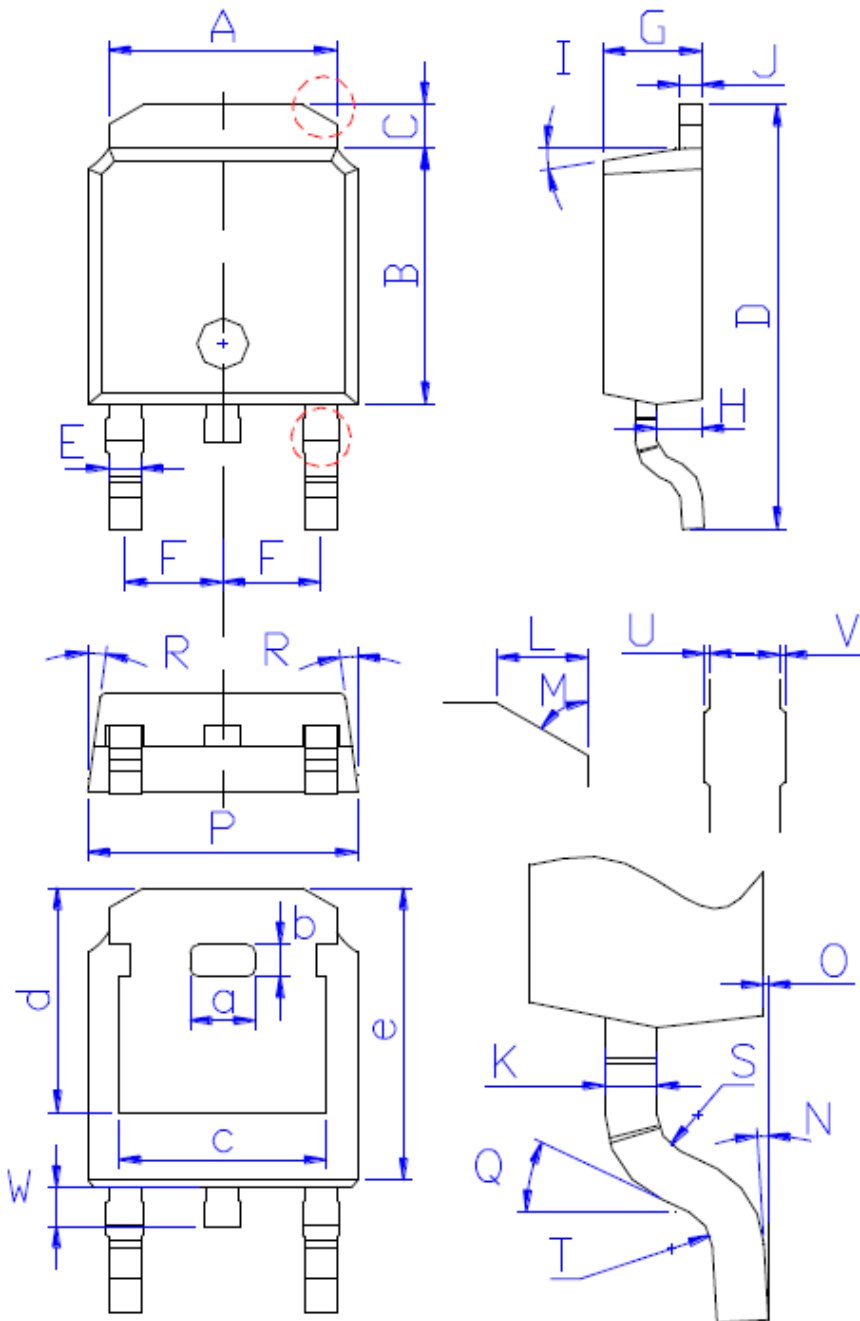
## Test circuit and waveform for diode characteristics





# Package Outline TO-252

TSD60R380S1 600V 10.6A N-Channel SJ-MOSFET



DIM	MILLIMETERS
A	$5.34 \pm 0.30$
B	$6.00 \pm 0.30$
C	$1.05 \pm 0.30$
D	$9.95 \pm 0.30$
E	$0.76 \pm 0.15$
F	$2.28 \pm 0.15$
G	$2.30 \pm 0.30$
H	$1.06 \pm 0.30$
I	$(4-10)^\circ$
J	$0.51 \pm 0.15$
K	$0.52 \pm 0.15$
L	$0.80 \pm 0.30$
M	$60^\circ$
N	$(0-10)^\circ$
O	$0.05 \pm 0.05$
P	$6.60 \pm 0.30$
Q	$25^\circ$
R	$(4-8.5)^\circ$
S	R0.40
T	R0.40
U	$0.05 \pm 0.05$
V	$0.05 \pm 0.05$
W	$0.90 \pm 0.30$
a	$1.80 \pm 0.30$
b	$0.75 \pm 0.30$
c	$4.85 \pm 0.30$
d	$5.30 \pm 0.30$
e	$6.90 \pm 0.30$